

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	196	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 "through-hole" "thru-hole" opening hole via) and (seed near5 layer) with \$4continuous	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 17:20
S2	196	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and (seed near5 layer) with \$4continuous	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 17:21
S3	76	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and (seed near5 layer) with (discontinuous noncontinuous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 17:35
S4	4	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and ((barrier liner) near5 layer) with (discontinuous noncontinuous) and (seed near5 layer) with (electroless)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 17:40
S5	165	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and ((barrier liner) near5 layer) and (seed near5 layer) with (electroless)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 17:40
S6	11	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and ((barrier liner) near5 layer) and (seed near5 layer) with (electroless) and (palladium platinum) near5 (activat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 17:42

S7	12	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and ((barrier liner) near5 layer) and (seed near5 layer) with (electroless) and (palladium platinum) near10 (activat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 18:06
S8	2	"08166"	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 18:00
S9	1584	\$5"08166"	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 18:00
S10	1205	\$2"08166"	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 18:01
S11	0	\$2"08166" and pct	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 18:01
S12	67	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and ((barrier liner) near5 layer) and (seed near5 layer) with (electroless) and (palladium platinum) near10 (activat\$4) not S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 18:21
S13	57	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and ((barrier liner) near5 layer) and (seed near5 layer) with (electroless) and (palladium platinum) near10 (activat\$4) and (cmp polish\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 18:22
S14	57	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (trench microvia recess\$3 opening hole via) and ((barrier liner) near5 layer) and (seed near5 layer) with (electroless) and (palladium platinum) near10 (activat\$4) and (cmp polish\$3) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/25 18:23